

MBS Plastic-Encapsulate Bridge Rectifier

Features

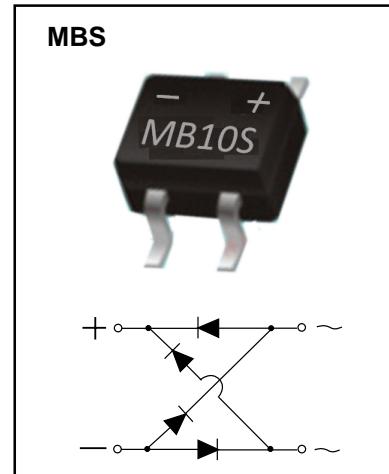
- I_o 0.8A
- V_{RRM} 50V-1000V
- High surge current capability
- Glass passivated chip
- Polarity: Color band denotes cathode

Applications

- General purpose 1 phase Bridge rectifier applications

Marking

- MBXXS
- X : From 05 To 10



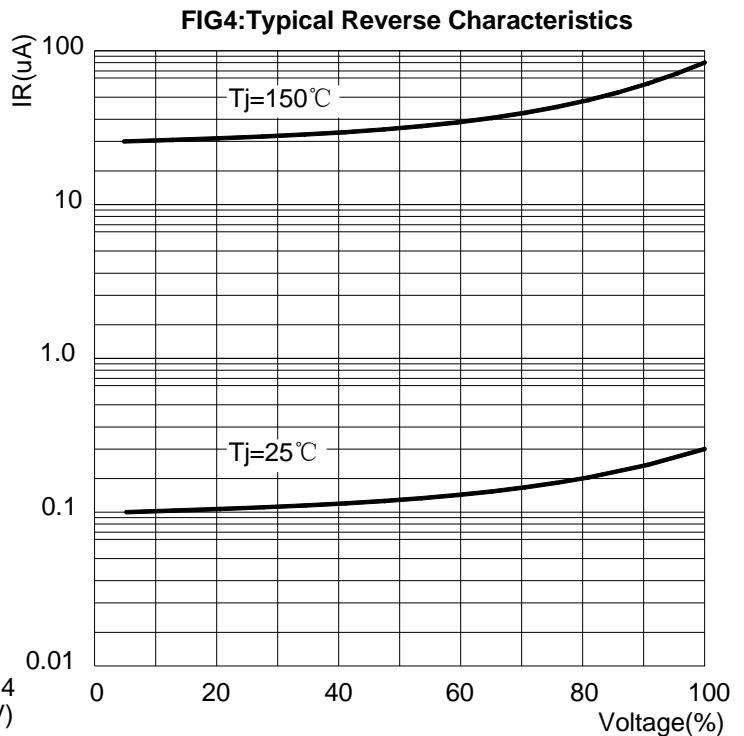
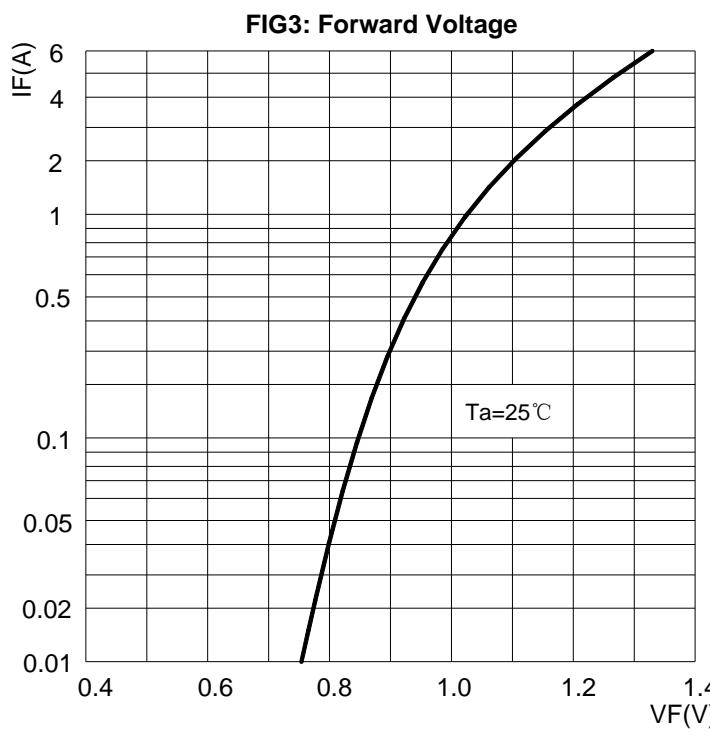
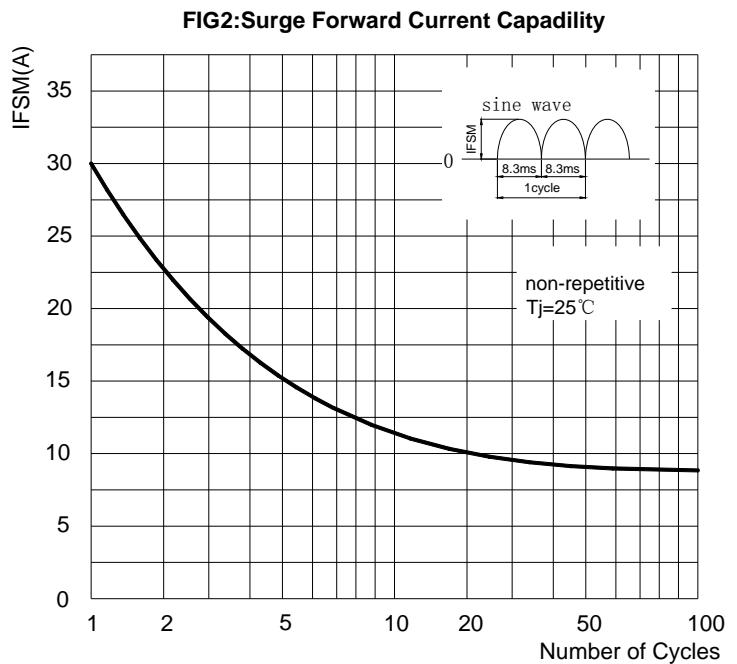
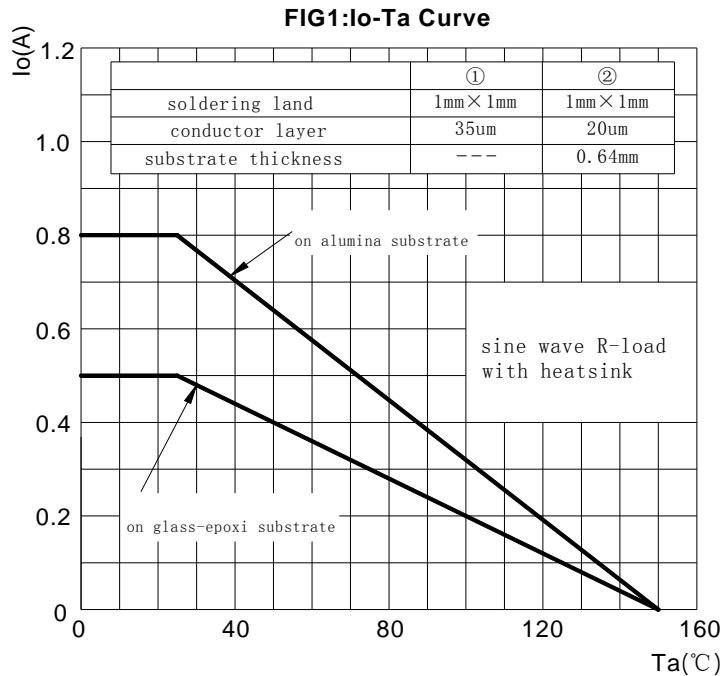
Limiting Values (Absolute Maximum Rating)

Item	Symbol	Unit	Conditions	MB										
				05S	1S	2S	4S	6S	8S	10S				
Repetitive Peak Reverse Voltage	V_{RRM}	V		50	100	200	400	600	800	1000				
Maximum RMS Voltage	V_{RMS}	V		35	70	140	280	420	560	700				
Average Rectified Output Current	I_o	A	60Hz sine wave, R-load, $T_a=25^\circ C$	On alumina substrate			0.8							
				On glass-epoxi substrate			0.5							
Surge(Non-repetitive)Forward Current	I_{FSM}	A	60Hz sine wave, 1 cycle, $T_j=25^\circ C$	30										
Current Squared Time	I^2t	A^2S	$1ms \leq t < 8.3ms$ $T_j=25^\circ C$, Rating of per diode	3.7										
Storage Temperature	T_{stg}	$^\circ C$		-55 ~+150										
Junction Temperature	T_j	$^\circ C$		-55 ~+150										

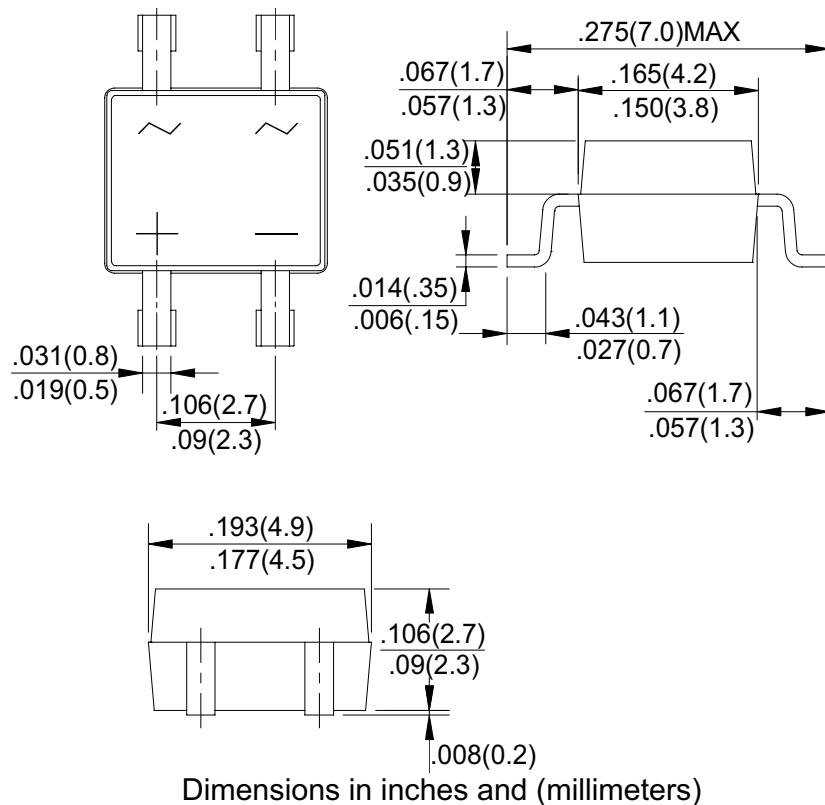
Electrical Characteristics ($T_a=25^\circ C$ Unless otherwise specified)

Item	Symbol	Unit	Test Condition	Max
Peak Forward Voltage	V_{FM}	V	$I_{FM}=0.8A$, Pulse measurement, Rating of per diode	1.0
Peak Reverse Current	I_{RRM}	μA	$V_{RM}=V_{RRM}$, Pulse measurement, Rating of per diode	10
Thermal Resistance	$R_{\theta J-A}$	$^\circ C/W$	Between junction and ambient, On alumina substrate	76
			Between junction and ambient, On glass-epoxi substrate	134
			Between junction and lead	20

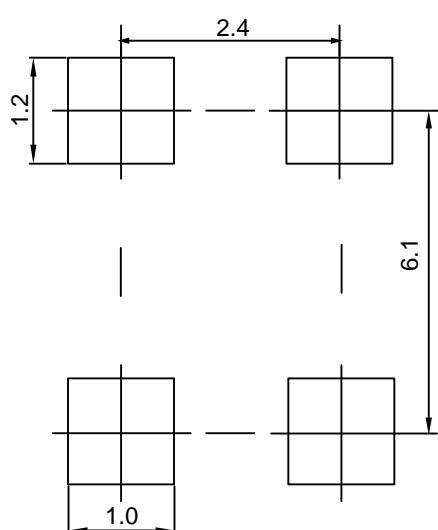
Typical Characteristics



MBS Package Outline Dimensions



MBS Suggested Pad Layout



Note:

1. Controlling dimension: in millimeters.
2. General tolerance: $\pm 0.05\text{mm}$.
3. The pad layout is for reference purposes only.

NOTICE

JSHD reserve the right to make modifications,enhancements, improvements, corrections or other changes without further notice to any product herein .JSHD does not assume any liability arising out of the application or use of any product described herein.

Reel Taping Specifications For Surface Mount Devices-MBS

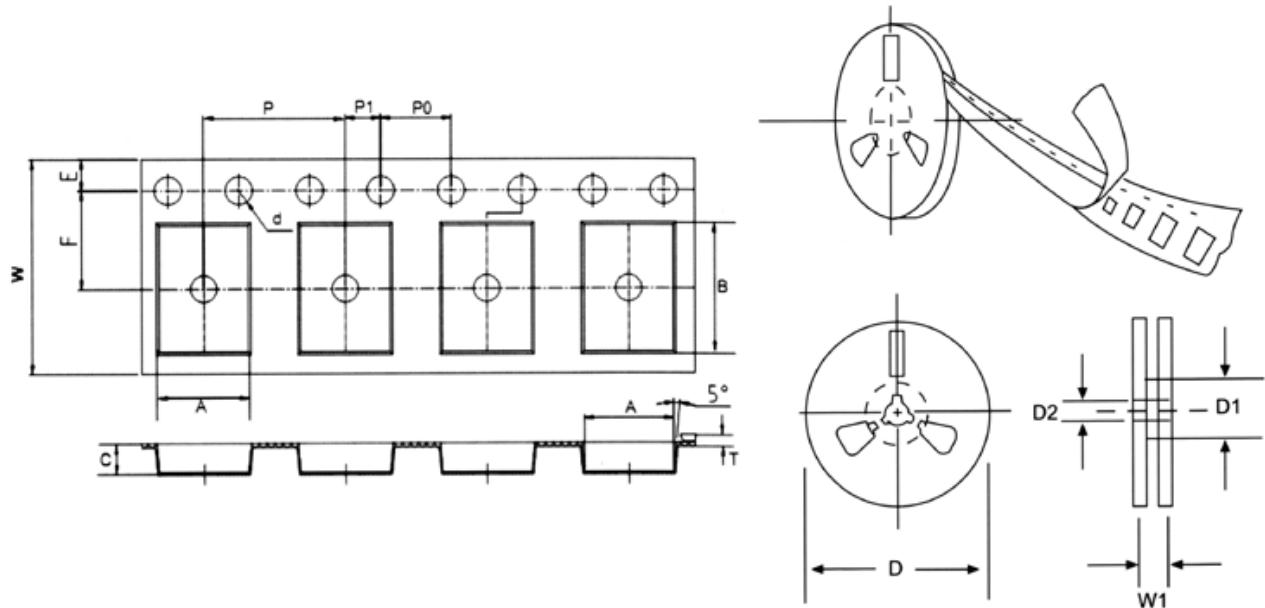


FIG:CONFIGURATION OF AXIAL TAPING

ITEM	SYMBOL	MBS mm(inch)
Carrier width	A	5.05+0.1(0.198+0.004)
Carrier length	B	7.22+0.1(0.284+0.004)
Carrier depth	C	2.88+0.1(0.113+0.004)
Sprocket hole	d	1.50+0.1(0.059+0.004/-0)
Reel outside diameter	D	330/281+2.0(13/11+0.279)
Reel inner diameter	D1	8.0+0.2(0.315+0.008)
Feed hole diameter	D2	13+0.5(0.512+0.020)
Stroket hole position	E	1.75+0.1(0.069+0.004)
Punch hole position	F	5.50+0.05(0.217+0.002)
Punch hole pitch	P	8.0+0.1(0.315+0.004)
Sprocket hole pitch	P0	4.0+0.1(0.157+0.004)
Embossment center	P1	2.0+0.1(0.079+0.004)
Total tape thickness	T	0.20-0.70(0.080-0.028)
Tape width	W	12.0+0.3/-0.1(0.472+0.004)
Reel width	W1	16.8+2.0(0.661+0.079)

NOTE:Devices are packde in accordance with EIA standard RS-481-A and specification given above.